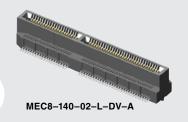




Mates with (1.60 mm)





(0.80 mm) .0315"

**MEC8-DV SERIES** 

Variety of

# ERTICAL MICRO EDGE CARD SO

#### **SPECIFICATIONS**

For complete specifications and recommended PCB layouts see www.samtec.com?MEC8-DV

Insulator Material: Black LCF

Contact Material:

Contact Material:
Phosphor Bronze
Plating:
Au or Sn over
50 µ" (1.27 µm) Ni
Operating Temp Range:
-55 °C to +125 °C
Insertion Depth:
(4.22 mm) .166" to
(5.66 mm) .223"
Current Bating:

Current Rating:

1.8 A per pin (6 adjacent pins powered) Voltage Rating: 185 VAC

RoHS Compliant: Yes

## **PROCESSING**

Lead-Free Solderable:

SMT Lead Coplanarity: (0.10 mm) .004" max (10-50) (0.15 mm) .006" max (60-70)

# **RECOGNITIONS**

For complete scope of recognitions see www.samtec.com/quality



## **ALSO AVAILABLE** (MOQ Required)

- 1 mm mating card thickness option
- · Locking clip (Manual placement required)

Contact Samtec.

# **OTHER** SOLUTIONS

- · Right-angle
- · Edge Mount

See samtec.com?MEC8-RA or samtec.com?MEC8-EM

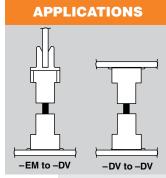
#### Notes:

While optimized for 50  $\Omega$  applications, this connector with alternative signal/ground patterns may also perform well in certain 75  $\Omega$  applications. Contact Samtec for further information.

Some sizes, styles and options are non-standard, non-returnable.

#### Mates with:

1.60 mm) .062" thick card



# .062" thick card lead counts F.F.F.F. (0.80 mm)

#### HIGH-SPEED CHANNEL PERFORMANCE

MEC8-DV

Rating based on Samtec reference channel. For full SI performance data visit Samtec.com or contact SIG@samtec.com

MEC8

**POSITIONS PER ROW** 

02

**PLATING** OPTION

.0315" pitch

DV

**OTHER OPTION** 

-A

= Alignment

Pin

-K = (5.50 mm)

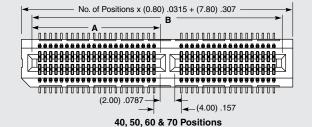
.217" DIA

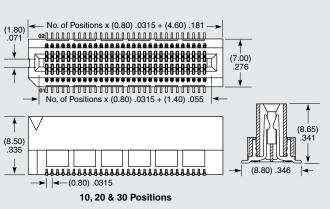
Polyimide Pick

& Place Pad

10, 20, 30, 40, 50, 60, 70

-L = 10 μ" (0.25 μm) Gold on contact, Matte Tin on tail





POSITIONS PER ROW В (18.90) .744 (36.60) 1.441 40 (44.60) (22.90)50 .902 1.756 (26.90 (52.60) 60 1 059 2.071 (60.60) (30.90)

(1.35) .053 (0.90) .035 DIA OPTION